

# OL-TFA9897A

wafer level chip-scale package; 30 bumps; 2.06 x 2.72 x 0.50 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP30
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-4-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.69	-	2.72	2.75	mm
E	package width	2.03	-	2.06	2.09	mm
A	seated height	0.45	-	0.5	0.55	mm
e	nominal pitch	-	-	0.4	-	m
n <sub>2</sub>	actual quantity of termination	-	-	30	-	



## 2. Package outline

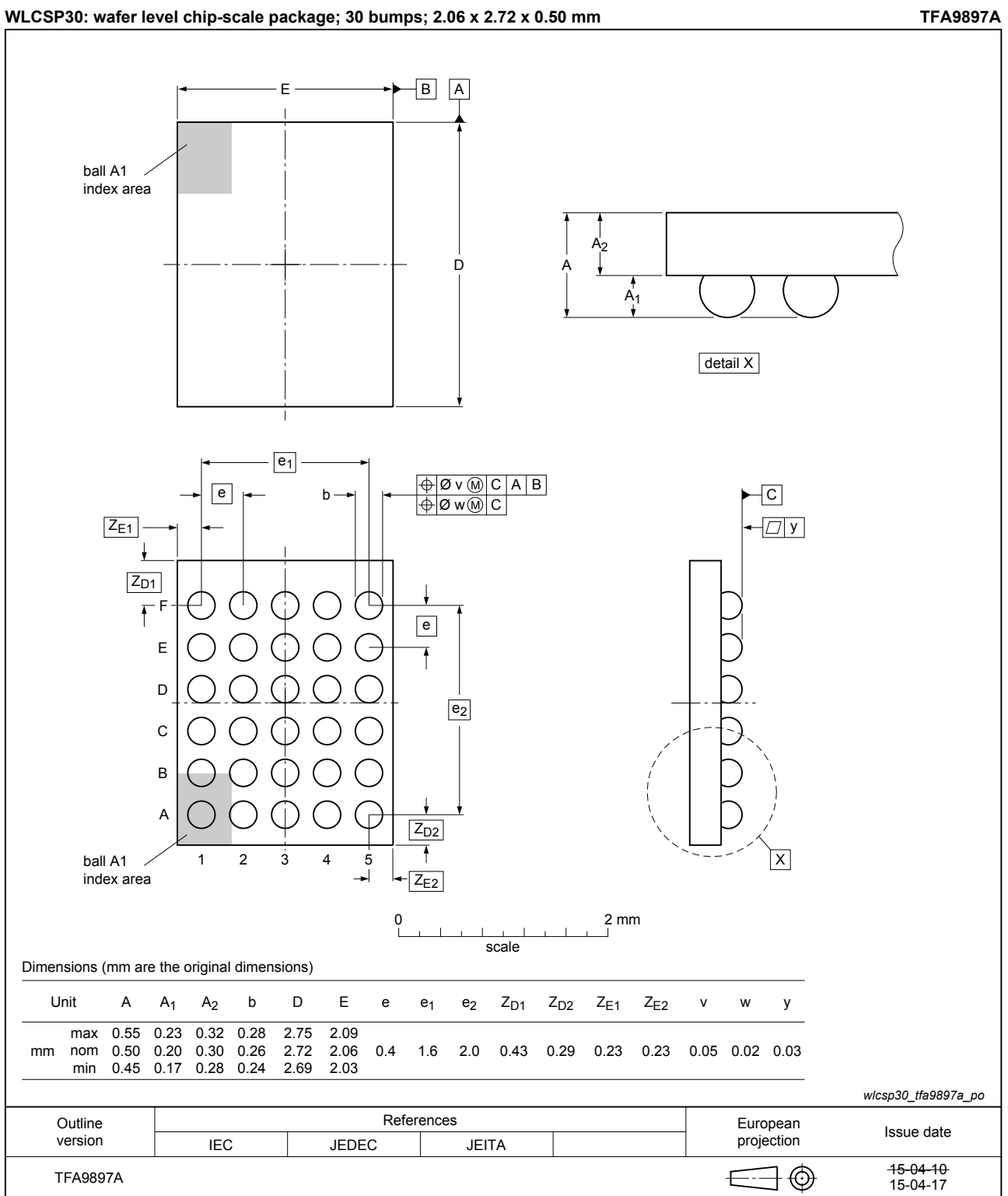


Fig. 1. Package outline WLCSP30 (OL-TFA9897A)

### 3. Legal information

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## 4. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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